a via metal extending therefrom where the openings contact the via metal. The substrate also has a discontinuous plating layer located within each of the openings and contacting the via metal. The substrate still further includes an electroplated contact layer located over each of the discontinuous plating layers where the electroplated contact layers are electrically connected to each other by the via metal."

A1 Contd

(2) Please amend the paragraph [0021] on page 9 as follows:

"[0021] Referring initially to FIGURE 1, illustrated is a sectional view of a portion of one embodiment of an IC substrate 100 manufactured according to the principles of the present invention. FIGURE 1 illustrates a sectional view of a portion of the substrate 100 early in the manufacturing process, and includes a conventional printed wiring board (PWB) 110 as its core. The PWB 110 provides structural support for the overall substrate 100 and, in exemplary embodiments, the core may be composed of Bismaleimide Triazine (BT), fiberglass, copper or other suitable, rigid material. Those skilled in the art understand the advantages associated with each of these materials, as well as other materials suitable for use as the core of the substrate 100."

A2

(3) Please amend the paragraph [0027] on page 13 as follows:

"[0027] Referring now to FIGURE 4, illustrated is a sectional view of a portion of one embodiment of the substrate 100 after an etch resist 410 has been applied to the bottom side of the substrate 100. As shown in FIGURE 4, the etch resist 410 is applied in the lower openings 320 of the substrate 100 to protect the plating layer 150 on the second side of the substrate 100. An etchant is applied to the substrate 100 to perform a quick etch to remove the portions of the

A3